

Silicon Photomultiplier, a new device for low light level photon detection

Outline

- •Concept of a Silicon Photomultiplier
- Advantages
- •Problems
- •Status of front-illuminated devices
- •Development of back-illuminated devices
- Conclusions



Silicon Photomultiplier

Basic building block: avalanche photodiode operating in Geiger mode



Device is operated above breakdown voltage Photon is absorbed in depleted silicon Electron (or hole) drifts into high field region Avalanche amplification (Geiger breakdown) Signal size ("amplification") given be overvoltage and cell capacity Q = C x ΔU (> 10⁶) Passive quenching by integrated resistor Single cell recovery ~ μ s (RC time to recharge)

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Single SiPM cell: binary signal of fixed size!

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Silicon Photomultiplier

Array of Cells connected to a single output:

Signal = Σ of cells fired

If probability to hit a single cell < 1 => **Signal proportional to # photons**





Array size: $0.5 \times 0.5 \text{ mm}^2$ to $5 \times 5 \text{ mm}^2$

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Silicon Photomultiplier

- •Single- & multiphoton peaks
- •"Self calibrating" photon counter"
- •Dynamic range ~ number of pixel

•Saturation for large signals





Advantages

- Simple, robust device
- Photon counting capability
- Easy calibration (counting)
- Insensitive to magnetic fields
- Fast response (< 1 ns)
- Large signal (only simple amplifier needed)



Magic Camera

- competitive quantum efficiency (~ 40% at 400-800 nm)
- No damage by accidental light
- Cheap (~ 10\$/unit)
- Low operation voltage (40 70 V)
- Many applications



Hadron Calorimeter for ILC



Problems/ R&D issues

- Sensitivity for blue light and UV
- Improve QE to >80%
- Cross Talk
- Dark rate





QE & Fill Factor

QE =

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x Geiger efficiency

x geometrical fill factor

Front illuminated devices:

Large area blinded by structures

- Al-contacts
- Resistor
- Guard rings

For 42 x 42 μ m² device: 15% fill factor

Solutions:

- larger pixel size
- back-Illumination
- (resistive bias layer)





3 µm light spot scanned across device





Cross talk

Hot carrier luminescence in avalanches: ~ 1 photon/10⁵ carriers (A. Lacaita, IEEE (1994)) Photons may trigger neighbor cells > 1 pixel/photon (excess noise)





Emission microscope picture





Problems: Cross talk

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Solutions:

•Lower gain (reduces QE)

•Optical insulation of cell (trenches)



x-talk measurements with special teststructures (MEPhI/Pulsar)

x 100 suppression possible







Problems: blue/UV sensitivity

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Electrons have a higher probability to trigger an avalanche breakdown then holes

Solutions:

Avalanche Efficiency (1 µm high field region)





Problems: Dark Rate

Thermally generated currents: Dark Rate

- Increases with overvoltage/gain (larger depleted area; tunneling)
- problem for large area devices (~50 MHz for 5x5 mm² at room temp.)
- cooling helps (but beware of afterpulsing due to trapping)





Optimization Matrix

Optimization of many parameters possible. Depends on applications

HG. Mose Max-Planck-Ins	er stitut	Pixel Size	Overvoltage	trenches
for Physics Munich	s, QE	 Better fill factor 	+ Better geiger efficency	 Reduced fill factor
	UV response		+ Better geiger efficency (holes)	
	X-talk	+ Larger gain	+ Larger gain	Optical insulation
	Dynamic range	Less pixel		
	Dark rate		+ Increase currents	+(?)
	Gain	+ Larger capacitance	+ Q = C x ΔU	

There are cross correlations:

e.g. trenches reduce x-talk, which allows to increase the overvoltage improving QE and UV response



for Physics, Munich

Overview

SiPMs are produced (but not necessarily commercially available) by:

- CPTA Moscow
- Max-Planck-Institut MEPhI/Pulsar, Moscow
 - Dubna/Micron (MSR, Metal Resistive Layer)
 - Hamamatsu, Japan ("MPPC"): 1 x 1 mm² 100 1600 pixel (100 mm 25 mm)
 - SensL, Irland: 1x1 mm2, ?? pixel



Hamamatsu MPPC 1 x 1 mm², 100 pixel







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New concept: backside illuminated SiPM

Photons enter through unstructured backside

Lateral drift field focuses electrons into small geiger region



Developed & (to be) produced at MPI Semiconductor Laboratory, Munich



Backside Illuminated SDD

Advantages:

- Unstructured thin entrance window
- 100% fill factor
- High conversion efficiency (especially at short wavelength)
- Lateral drift field focuses electrons into high field region
- High Geiger efficiency (always electrons trigger breakdown)
- Small diode capacitance (short recovery, reduced x-talk)

Expect high QE (>80%) in large wavelength range (300 nm-1000nm, depending on engineering of entrance window)





Backside Illuminated SDD

Disadvantages:

Large volume for thermal generated currents (increased dark rate)

Maintain low leakage currents Cooling Thinning (< 50 μm instead of 450 μm)

• Large volume for internal photon conversion (increases x-talk)

Lower gain (small diode capacitance helps) Thinning

• Electron drift increases time jitter

Small pixels, Increased mobility at low temperature <2 ns possible





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Project Status

First test structures have been produced at the MPI semiconductor lab

Evaluation (proof of principle) ongoing

"Real" prototypes to be produced 2006/2007

Final devices planned to be used in MAGIC upgrade





400 pixel array

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Single cell with resistor and Coupling capacitor



Conclusions

SiPM are a novel detector for low level light detection

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photon counting capability simple, robust easy to operate cheap

Ongoing R&D to improve:

cross talk (trenches,...) UV/blue sensitivity (inverted structures,...) QE (backside illumination,..)

Will replace photomultiplier tubes in many applications - see ILC session (CALICE)